

- 4 194 304 words by 32-bit organized SIMM modules for PC main memory applications
- Fast access and cycle time
 - 50 ns access time
 - 84 ns cycle time (-50 version)
 - 60 ns access time
 - 104 ns cycle time (-60 version)
- Hyper page mode (EDO) capability
 - 20 ns cycle time (-50 version)
 - 25 ns cycle time (-60 version)
- Single + 5 V ($\pm 10\%$) supply
- Low power dissipation
 - max. 5280 mW active (HYM 324025S/GS-50)
 - max. 4840 mW active (HYM 324025S/GS-60)
 - CMOS – 44 mW standby
 - TTL – 88 mW standby
- $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh
 - $\overline{\text{RAS}}$ -only-refresh
 - Hidden-refresh
- 8 decoupling capacitors mounted on substrate
- All inputs, outputs and clocks fully TTL compatible
- 72 pin Single in-Line Memory Module with 22.86 mm (900 mil) height
- Utilizes eight 4Mx4-DRAMs in 300mil wide SOJ packages
- 2048 refresh cycles / 32 ms
- Optimized for use in byte-write non-parity applications
- Tin-Lead contact pads (S - version)
- Gold contact pads (GS - version)

The HYM 324025S/GS-50/-60 is a 16 MByte DRAM module organized as 4 194 304 words by 32-bit in a 72-pin single-in-line package comprising eight HYB 5117405BJ 4M x 4 DRAMs in 300 mil wide SOJ-packages mounted together with eight 0.2 μ F ceramic decoupling capacitors on a PC board.

Each HYB 5117405BJ is described in the data sheet and is fully electrical tested and processed according to SIEMENS standard quality procedure prior to module assembly. After assembly onto the board, a further set of electrical tests is performed.

The speed of the module can be detected by the use of four presence detect pins.

The common I/O feature on the HYM 324025S/GS-50/-60 dictates the use of early write cycles.

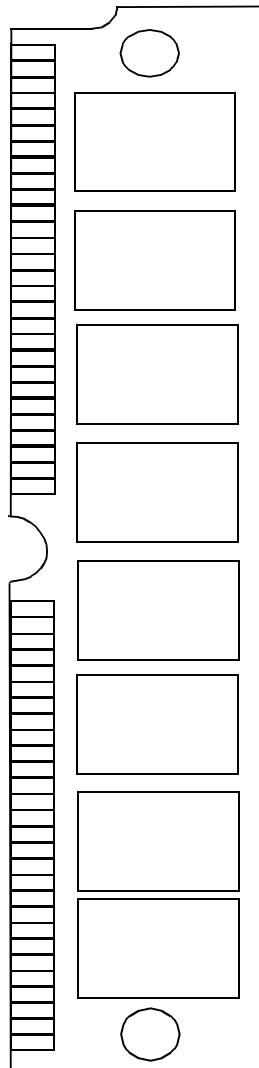
Ordering Information

Type	Ordering Code	Package	Description
HYM 324025S-50	Q67100-Q2156	L-SIM-72-12	EDO - DRAM Module (access time 50 ns)
HYM 324025S-60	Q67100-Q2157	L-SIM-72-12	EDO - DRAM Module (access time 60 ns)
HYM 324025GS-50	Q67100-Q2096	L-SIM-72-12	EDO - DRAM Module (access time 50 ns)
HYM 324025GS-60		L-SIM-72-12	EDO - DRAM Module (access time 60 ns)

Pin Configuration

VSS 1 DQ0 2
 DQ16 3 DQ1 4
 DQ17 5 DQ2 6
 DQ18 7 DQ3 8
 DQ19 9 VCC 10
 N.C. 11 A0 12
 A1 13 A2 14
 A3 15 A4 16
 A5 17 A6 18
 A10 19 DQ4 20
 DQ20 21 DQ5 22
 DQ21 23 DQ6 24
 DQ22 25 DQ7 26
 DQ23 27 A7 28
 N.C. 29 VCC 30
 A8 31 A9 32
 N.C. 33 $\overline{\text{RAS2}}$ 34
 N.C. 35 N.C. 36

N.C. 37 N.C. 38
 VSS 39 $\overline{\text{CAS0}}$ 40
 $\overline{\text{CAS2}}$ 41 $\overline{\text{CAS3}}$ 42
 $\overline{\text{CAS1}}$ 43 $\overline{\text{RAS0}}$ 44
 N.C. 45 N.C. 46
 $\overline{\text{WE}}$ 47 N.C. 48
 DQ8 49 DQ24 50
 DQ9 51 DQ25 52
 DQ10 53 DQ26 54
 DQ11 55 DQ27 56
 DQ12 57 DQ28 58
 VCC 59 DQ29 60
 DQ13 61 DQ30 62
 DQ14 63 DQ31 64
 DQ15 65 N.C. 66
 PD0 67 PD1 68
 PD2 69 PD3 70
 N.C. 71 VSS 72

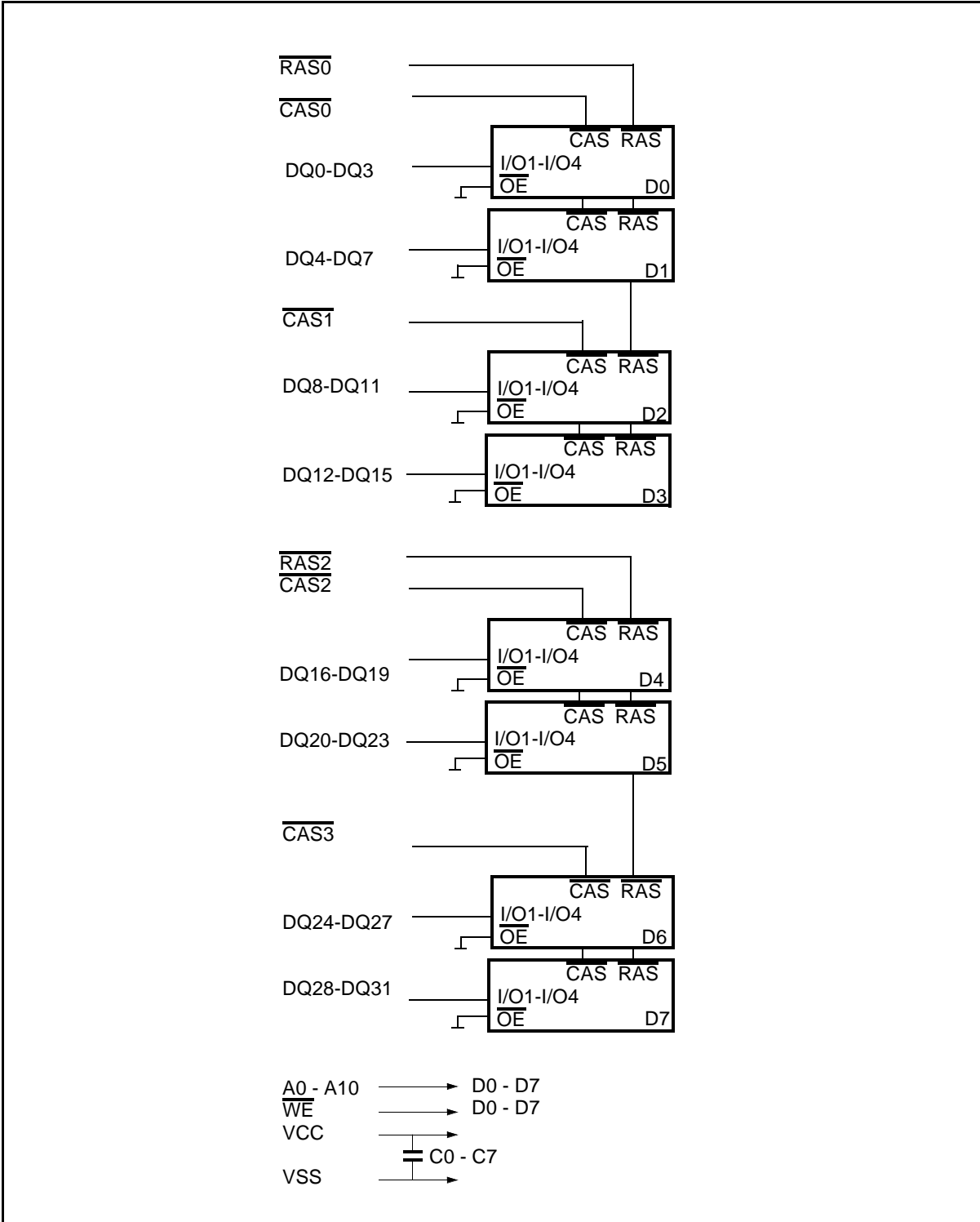


Pin Names

A0-A10	Address Inputs for HYM 324025S/GS
DQ0-DQ31	Data Input/Output
$\overline{\text{CAS0}}$ - $\overline{\text{CAS3}}$	Column Address Strobe
$\overline{\text{RAS0}}$, $\overline{\text{RAS2}}$	Row Address Strobe
$\overline{\text{WE}}$	Read/Write Input
V_{CC}	Power (+ 5 V)
V_{SS}	Ground
PD	Presence Detect Pin
N.C.	No Connection

Presence Detect Pins

	-50	-60
PD0	V_{SS}	V_{SS}
PD1	N.C.	N.C.
PD2	V_{SS}	N.C.
PD3	V_{SS}	N.C.



Block Diagram

Absolute Maximum Ratings

Operation temperature range	0 to + 70 °C
Storage temperature range.....	- 55 to 125 °C
Input/output voltage	-0.5V to min (V _{CC} +0.5, 7.0) V
Power supply voltage.....	- 1 to + 7 V
Power dissipation.....	6.72 W
Data out current (short circuit)	50 mA

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage of the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC Characteristics

T_A = 0 to 70 °C, V_{CC} = 5 V ± 10 %

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Input high voltage	V _{IH}	2.4	V _{CC} +0.5	V	1)
Input low voltage	V _{IL}	- 0.5	0.8	V	1)
Output high voltage (I _{OUT} = - 5 mA)	V _{OH}	2.4	-	V	1)
Output low voltage (I _{OUT} = 4.2 mA)	V _{OL}	-	0.4	V	1)
Input leakage current (0 V < V _{IN} < 6.5 V, all other pins = 0 V)	I _{I(L)}	- 20	20	µA	1)
Output leakage current (DO is disabled, 0 V < V _{OUT} < 5.5 V)	I _{O(L)}	- 10	10	µA	1)
Average V _{CC} supply current (\overline{RAS} , \overline{CAS} , address cycling, t _{RC} = t _{RC} min) 50 ns - Version 60 ns - Version	I _{CC1}	-	960 880	mA mA	2) 3) 4)
Standby V _{CC} supply current ($\overline{RAS} = \overline{CAS} = V_{IH}$)	I _{CC2}	-	16	mA	
Average V _{CC} supply current during \overline{RAS} only refresh cycles (\overline{RAS} cycling, $\overline{CAS} = V_{IH}$, t _{RC} = t _{RC} min) 50 ns - Version 60 ns - Version	I _{CC3}	-	960 880	mA mA	2) 4)

DC Characteristics¹⁾ (cont'd)

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Average V_{CC} supply current during hyper page mode (EDO) ($\overline{RAS} = V_{IL}$, \overline{CAS} , address cycling, $t_{HPC} = t_{HPC} \text{ min}$) 50 ns - Version 60 ns - Version	I_{CC4}	– –	560 440	mA mA	2) 3) 4)
Standby V_{CC} supply current ($\overline{RAS} = \overline{CAS} = V_{CC} - 0.2 \text{ V}$)	I_{CC5}	–	8	mA	1)
Average V_{CC} supply current during \overline{CAS} -before- \overline{RAS} refresh mode (\overline{RAS} , \overline{CAS} cycling, $t_{RC} = t_{RC} \text{ min}$) 50 ns - Version 60 ns - Version	I_{CC6}	– –	960 880	mA mA	2) 4)

Capacitance

$T_A = 0 \text{ to } 70 \text{ }^\circ\text{C}$, $V_{CC} = 5 \text{ V} \pm 10 \%$, $f = 1 \text{ MHz}$

Parameter	Symbol	Limit Values		Unit
		min.	max.	
Input capacitance (A0 to A10, \overline{WE})	C_{11}	–	75	pF
Input capacitance ($\overline{RAS0}$, $\overline{RAS2}$)	C_{12}	–	45	pF
Input capacitance ($\overline{CAS0}$ - $\overline{CAS3}$)	C_{13}	–	25	pF
I/O capacitance (DQ0-DQ31)	C_{10}	–	15	pF

AC Characteristics ⁵⁾⁶⁾

$T_A = 0$ to 70 °C, $V_{CC} = 5$ V \pm 10 %, $t_T = 2$ ns

Parameter	Symbol	Limit Values				Unit	Note
		-50		-60			
		min.	max.	min.	max.		

common parameters

Random read or write cycle time	t_{RC}	84	–	104	–	ns	
\overline{RAS} precharge time	t_{RP}	30	–	40	–	ns	
\overline{RAS} pulse width	t_{RAS}	50	10k	60	10k	ns	
\overline{CAS} pulse width	t_{CAS}	8	10k	10	10k	ns	
Row address setup time	t_{ASR}	0	–	0	–	ns	
Row address hold time	t_{RAH}	8	–	10	–	ns	
Column address setup time	t_{ASC}	0	–	0	–	ns	
Column address hold time	t_{CAH}	8	–	10	–	ns	
\overline{RAS} to \overline{CAS} delay time	t_{RCD}	12	37	14	45	ns	
\overline{RAS} to column address delay time	t_{RAD}	10	25	12	30	ns	
\overline{RAS} hold time	t_{RSH}	13		15	–	ns	
\overline{CAS} hold time	t_{CSH}	40		50	–	ns	
\overline{CAS} to \overline{RAS} precharge time	t_{CRP}	5	–	5	–	ns	
Transition time (rise and fall)	t_T	1	50	1	50	ns	7
Refresh period	t_{REF}	–	32	–	32	ms	

Read Cycle

Access time from \overline{RAS}	t_{RAC}	–	50	–	60	ns	8, 9
Access time from \overline{CAS}	t_{CAC}	–	13	–	15	ns	8, 9
Access time from column address	t_{AA}	–	25	–	30	ns	8,10
Column address to \overline{RAS} lead time	t_{RAL}	25	–	30	–	ns	
Read command setup time	t_{RCS}	0	–	0	–	ns	
Read command hold time	t_{RCH}	0	–	0	–	ns	11
Read command hold time referenced to \overline{RAS}	t_{RRH}	0	–	0	–	ns	11
\overline{CAS} to output in low-Z	t_{CLZ}	0	–	0	–	ns	8
Output buffer turn-off delay	t_{OFF}	0	13	0	15	ns	12

AC Characteristics (cont'd) ⁵⁾⁶⁾

$T_A = 0$ to 70 °C, $V_{CC} = 5$ V \pm 10 %, $t_T = 2$ ns

Parameter	Symbol	Limit Values				Unit	Note
		-50		-60			
		min.	max.	min.	max.		

Early Write Cycle

Write command hold time	t_{WCH}	8	–	10	–	ns	
Write command pulse width	t_{WP}	8	–	10	–	ns	
Write command setup time	t_{WCS}	0	–	0	–	ns	13
Write command to \overline{RAS} lead time	t_{RWL}	13	–	15	–	ns	
Write command to \overline{CAS} lead time	t_{CWL}	13	–	15	–	ns	
Data setup time	t_{DS}	0	–	0	–	ns	14
Data hold time	t_{DH}	8	–	10	–	ns	14

Hyper Page Mode (EDO) Cycle

Hyper page mode (EDO) cycle time	t_{HPC}	20	–	25	–	ns	
\overline{CAS} precharge time	t_{CP}	8	–	10	–	ns	
Access time from \overline{CAS} precharge	t_{CPA}	–	27	–	32	ns	7
Output data hold time	t_{COH}	5	–	5	–	ns	
\overline{RAS} pulse width in hyper page mode	t_{RAS}	50	200k	60	200k	ns	
\overline{CAS} precharge to \overline{RAS} Delay	t_{RHCP}	27	–	32	–	ns	

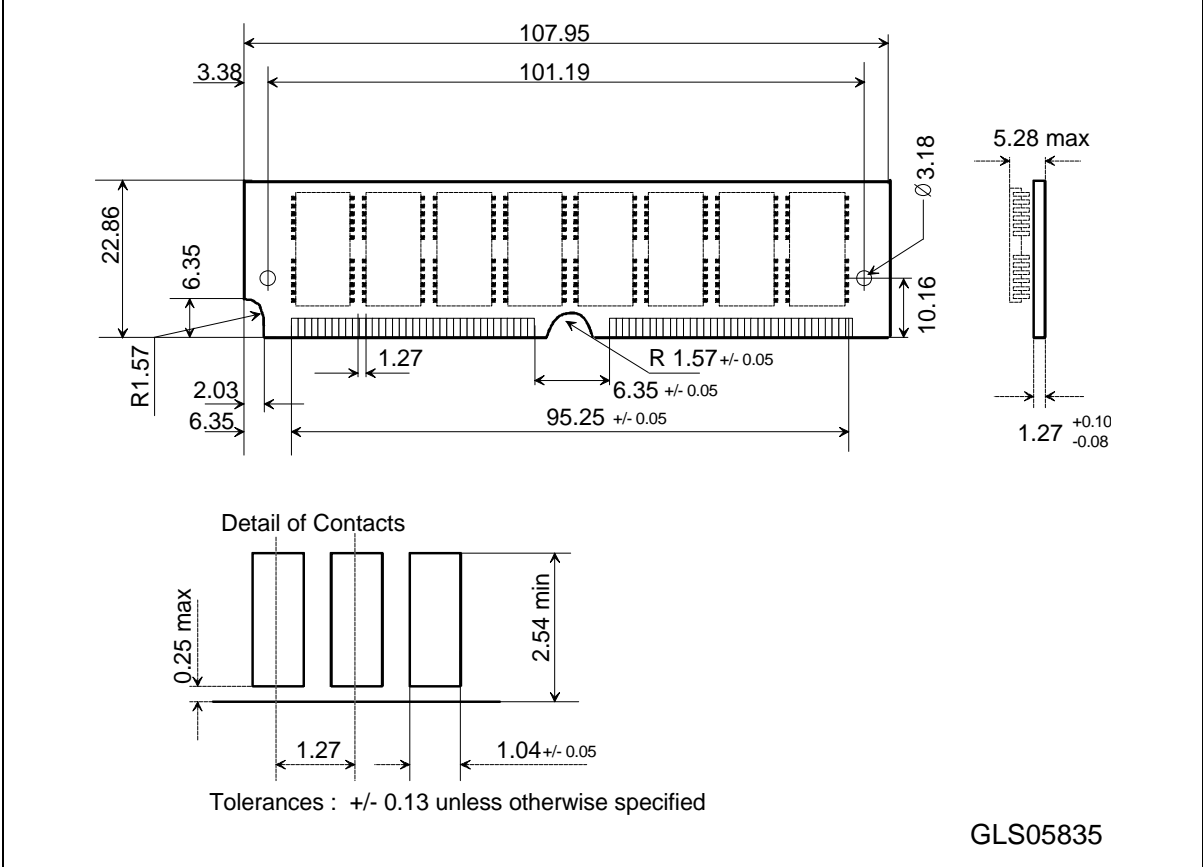
\overline{CAS} before \overline{RAS} Refresh Cycle

\overline{CAS} setup time	t_{CSR}	10	–	10	–	ns	
\overline{CAS} hold time	t_{CHR}	10	–	10	–	ns	
\overline{RAS} to \overline{CAS} precharge time	t_{RPC}	5	–	5	–	ns	
Write to \overline{RAS} precharge time	t_{WRP}	10	–	10	–	ns	
Write hold time referenced to \overline{RAS}	t_{WRH}	10	–	10	–	ns	

Notes:

- 1) All voltages are referenced to V_{SS} .
Vil may undershoot to -2.0 V for pulse width of less than or equal to 4 ns. Pulse width is measured at 50% points with amplitude measured peak to the DC reference.
- 2) I_{CC1} , I_{CC3} , I_{CC4} and I_{CC6} depend on cycle rate.
- 3) I_{CC1} and I_{CC4} depend on output loading. Specified values are obtained with the output open.
- 4) Address can be changed once or less while RAS = Vil. In case of ICC4 it can be changed once or less during a hyper page mode (EDO) cycle.
- 5) An initial pause of 200 μ s is required after power-up followed by 8 $\overline{\text{RAS}}$ cycles of which at least one cycle has to be a refresh cycle, before proper device operation is achieved. In case of using the internal refresh counter, a minimum of 8 $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ initialization cycles instead of 8 $\overline{\text{RAS}}$ cycles are required.
- 6) AC measurements assume $t_T = 2$ ns.
- 7) $V_{IH (min.)}$ and $V_{IL (max.)}$ are reference levels for measuring timing of input signals. Transition times are also measured between V_{IH} and V_{IL} .
- 8) Measured with the specified current load and 100 pF at Vol = 0.8 V and Voh = 2.0 V. Access time is determined by the latter of t_{RAC} , t_{CAC} , t_{AA} , t_{CPA} . t_{CAC} is measured from tristate.
- 9) Operation within the $t_{RCD (max.)}$ limit ensures that $t_{RAC (max.)}$ can be met. $t_{RCD (max.)}$ is specified as a reference point only. If t_{RCD} is greater than the specified $t_{RCD (max.)}$ limit, then access time is controlled by t_{CAC} .
- 10) Operation within the $t_{RAD (max.)}$ limit ensures that $t_{RAC (max.)}$ can be met. $t_{RAD (max.)}$ is specified as a reference point only. If t_{RAD} is greater than the specified $t_{RAD (max.)}$ limit, then access time is controlled by t_{AA} .
- 11) Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
- 12) $t_{OFF (max.)}$ define the time at which the output achieves the open-circuit conditions and are not referenced to output voltage levels. t_{OFF} is referenced from the rising edge of $\overline{\text{RAS}}$ or $\overline{\text{CAS}}$, whichever occurs last.
- 13) t_{WCS} is not a restrictive operating parameter. This is included in the data sheet as electrical characteristics only.
If $t_{WCS} > t_{WCS (min.)}$, the cycle is an early write cycle and data out pin will remain open-circuit (high impedance) through the entire cycle.
- 14) These parameters are referenced to the $\overline{\text{CAS}}$ leading edge.

Package Outline



Module Package, L-SIM-72-12
(Single in-Line Memory Module)